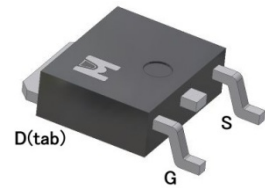
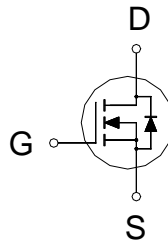


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV <sub>DSS</sub>	25V
R <sub>DS(on)</sub> (MAX.)	6mΩ
I <sub>D</sub>	80A



UIS, R<sub>g</sub> 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	80	A
	T <sub>C</sub> = 100 °C		50	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	170	
Avalanche Current		I <sub>AS</sub>	53	
Avalanche Energy	L = 0.1mH, I <sub>D</sub> =53A, R <sub>G</sub> =25Ω	E <sub>AS</sub>	140	mJ
Repetitive Avalanche Energy <sup>2</sup>	L = 0.05mH	E <sub>AR</sub>	40	
Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	69	W
	T <sub>C</sub> = 100 °C		27	
Operating Junction & Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

100% UIS testing in condition of V<sub>D</sub>=15V, L=0.1mH, V<sub>G</sub>=10V, I<sub>L</sub>=40A, Rated V<sub>DS</sub>=25V N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R <sub>θJC</sub>		1.8	°C / W
Junction-to-Ambient	R <sub>θJA</sub>		75	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle ≤ 1%



ELECTRICAL CHARACTERISTICS (T<sub>c</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	25			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	3	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μA
		V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C			25	
On-State Drain Current <sup>1</sup>	I <sub>D(ON)</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 10V	80			A
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A		5.3	6	mΩ
		V <sub>GS</sub> = 5V, I <sub>D</sub> = 24A		7.6	9.5	
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 24A		25		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz		1800		pF
Output Capacitance	C <sub>oss</sub>			480		
Reverse Transfer Capacitance	C <sub>rss</sub>			220		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 15mV, V <sub>DS</sub> = 0V, f = 1MHz		1.2		Ω
Total Gate Charge <sup>1,2</sup>	Q <sub>g</sub> (V <sub>GS</sub> =10V)	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A		34.5		nC
	Q <sub>g</sub> (V <sub>GS</sub> =5V)			22		
Gate-Source Charge <sup>1,2</sup>	Q <sub>gs</sub>			4.8		
Gate-Drain Charge <sup>1,2</sup>	Q <sub>gd</sub>			12.5		
Turn-On Delay Time <sup>1,2</sup>	t <sub>d(on)</sub>		V <sub>DS</sub> = 15V, I <sub>D</sub> = 25A, V <sub>GS</sub> = 10V, R <sub>GS</sub> = 2.7Ω		20	
Rise Time <sup>1,2</sup>	t <sub>r</sub>			15		
Turn-Off Delay Time <sup>1,2</sup>	t <sub>d(off)</sub>			50		
Fall Time <sup>1,2</sup>	t <sub>f</sub>			20		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>c</sub> = 25 °C)</b>						
Continuous Current	I <sub>S</sub>				80	A
Pulsed Current <sup>3</sup>	I <sub>SM</sub>				170	
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = I <sub>S</sub> , V <sub>GS</sub> = 0V			1.3	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = I <sub>S</sub> , dI <sub>F</sub> /dt = 100A / μS		32		nS
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			200		A
Reverse Recovery Charge	Q <sub>rr</sub>			12		nC

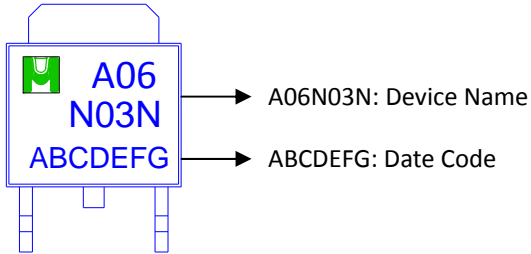
<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Pulse width limited by maximum junction temperature.

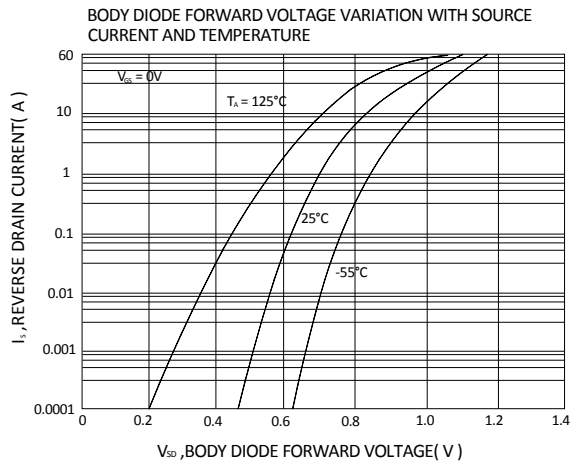
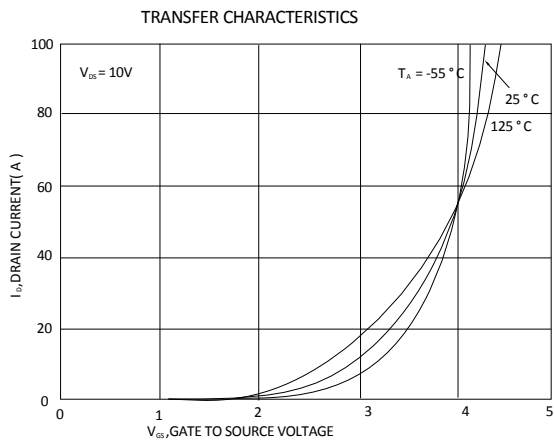
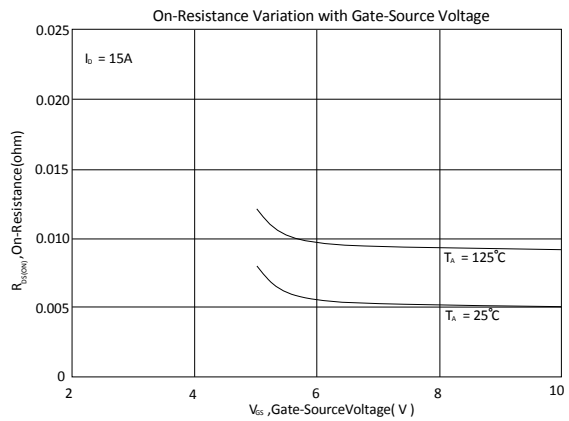
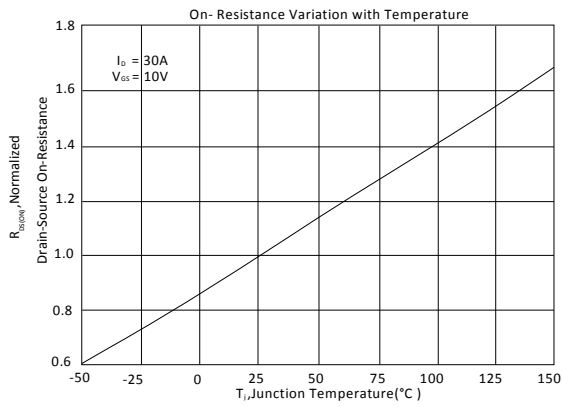
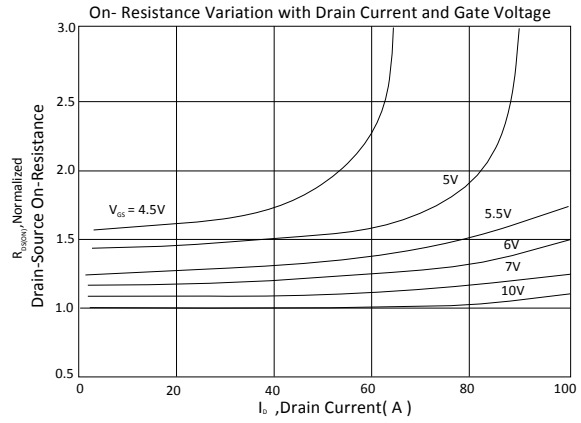
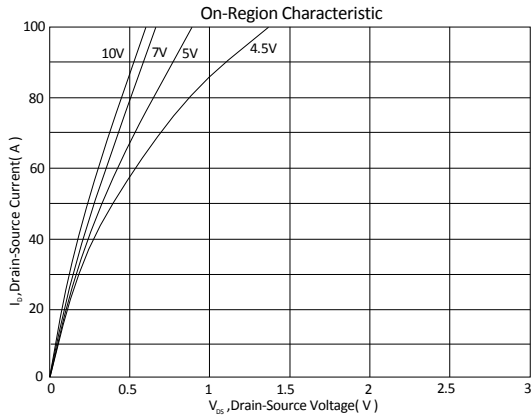
Ordering & Marking Information:

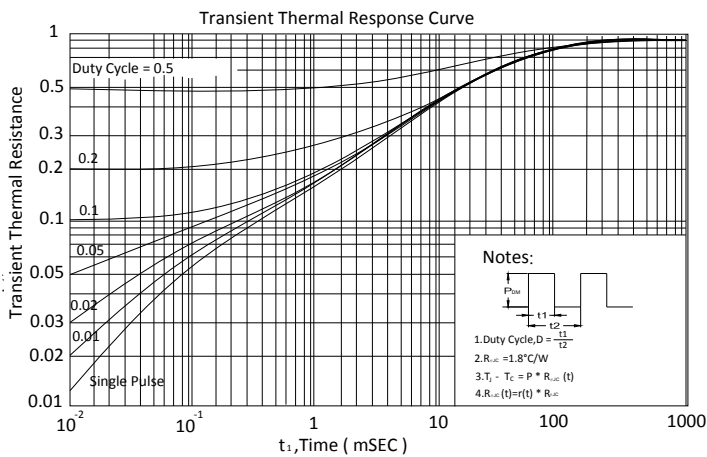
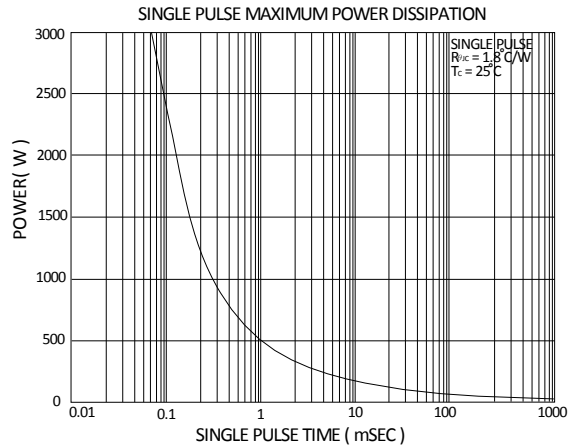
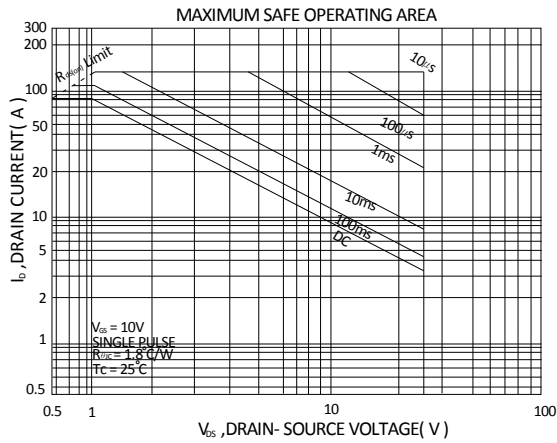
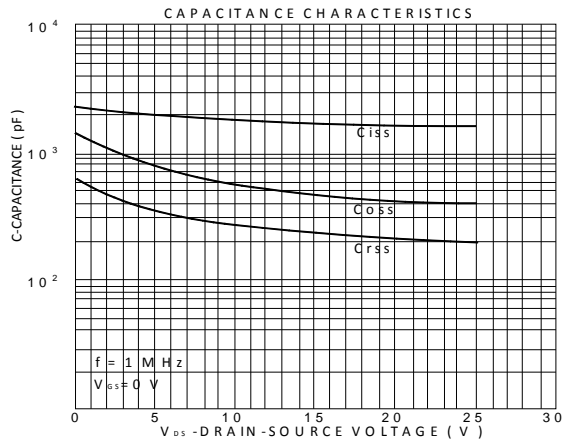
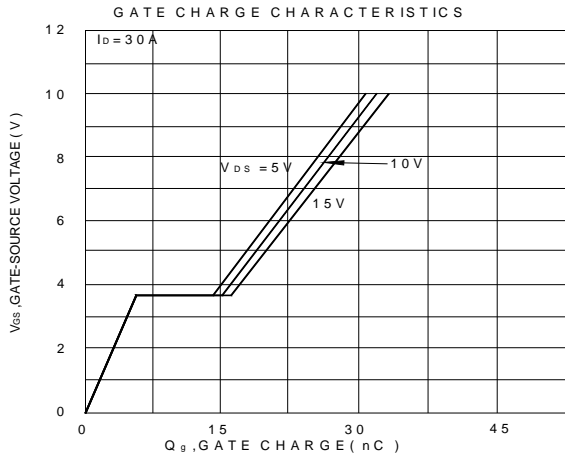
Device Name: EMA06N03AN for DPAK (TO-252)





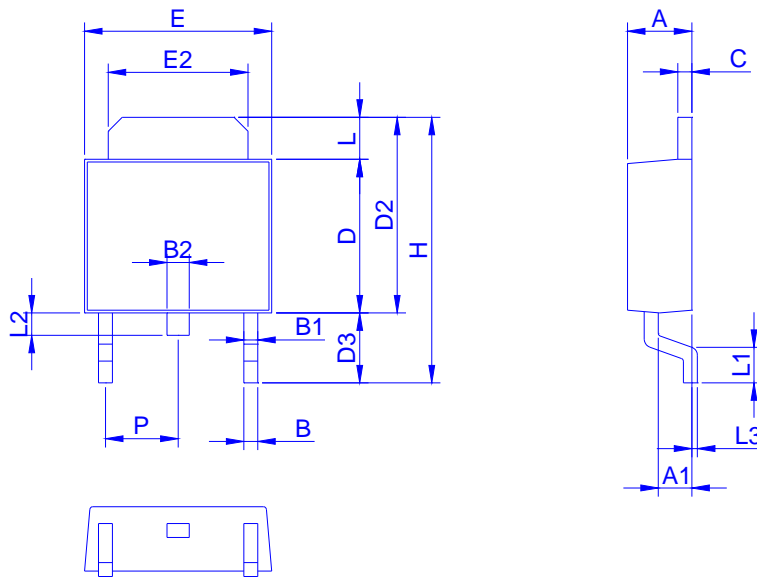
TYPICAL CHARACTERISTICS







Outline Drawing



Dimension	A	A1	B	B1	B2	C	D	D2	D3	E	E2	H	L	L1	L2	L3	P
Min.	2.10	0.95	0.30	0.40	0.60	0.40	5.30	6.70	2.20	6.40	4.80	9.20	0.89	0.90	0.50	0.00	2.10
Max.	2.50	1.30	0.85	0.94	1.00	0.60	6.20	7.30	3.00	6.70	5.45	10.15	1.70	1.65	1.10	0.30	2.50

Footprint

